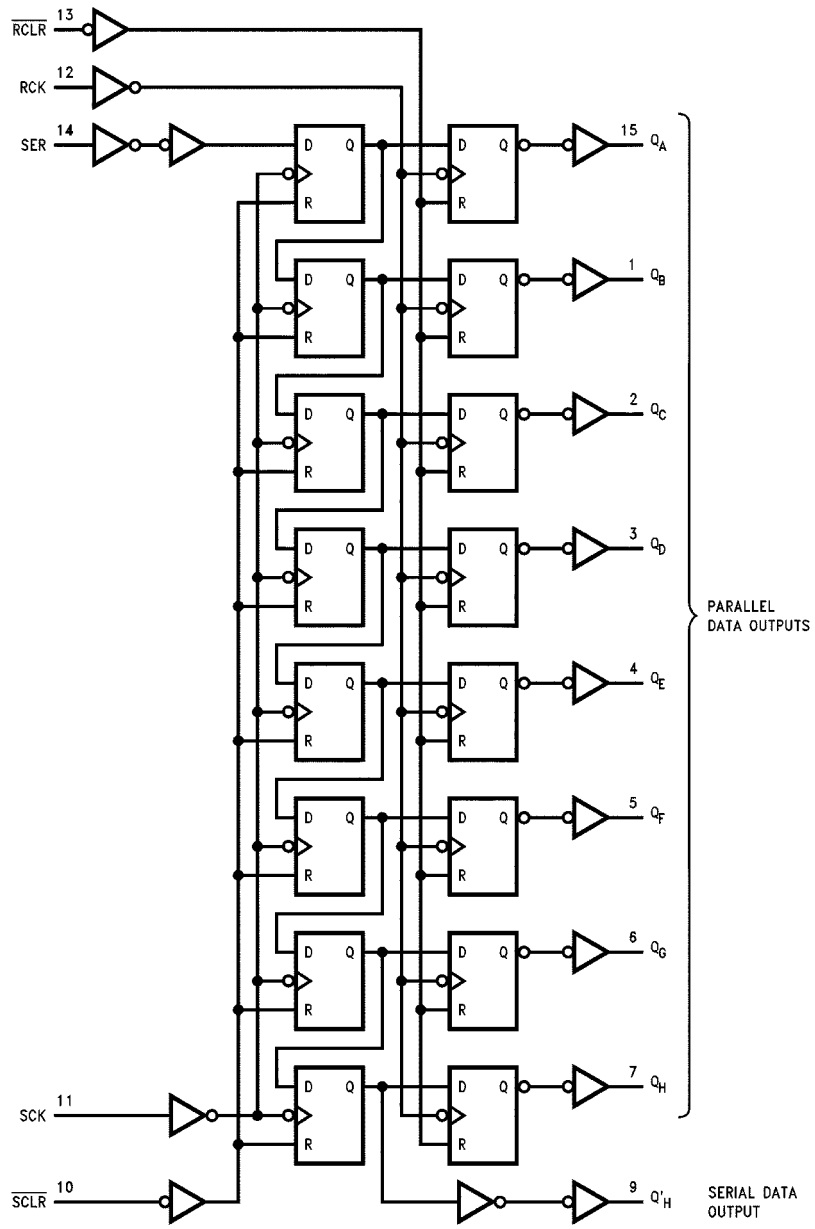


Logic Diagram



Absolute Maximum Ratings (Note 1)

(Note 2)

Supply Voltage (V_{CC})	-0.5 to +7.0V
DC Input Voltage (V_{IN})	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V_{OUT})	-0.5 to $V_{CC} + 0.5V$
Clamp Diode Current (I_{IK}, I_{OK})	± 20 mA
DC Output Current, per pin (I_{OUT})	± 35 mA
DC V_{CC} or GND Current, per pin (I_{CC})	± 70 mA
Storage Temperature Range (T_{STG})	-65°C to +150°C
Power Dissipation (P_D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T_L)	
(Soldering 10 seconds)	260°C

Recommended Operation Conditions

	Min	Max	Units
Supply Voltage (V_{CC})	2	6	V
DC Input or Output Voltage (V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T_A)	-40	+85	°C
Input Rise or Fall Times (t_r, t_f)			
$V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating—plastic "N" package: -12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^\circ\text{C}$		$T_A = -40 \text{ to } 85^\circ\text{C}$		Units
				Typ	Guaranteed Limits			
V_{IH}	Minimum HIGH Level Input Voltage		2.0V		1.5	1.5	V	
			4.5V		3.15	3.15		
			6.0V		4.2	4.2		
V_{IL}	Maximum LOW Level Input Voltage		2.0V		0.5	0.5	V	
			4.5V		1.35	1.35		
			6.0V		1.8	1.8		
V_{OH}	Minimum HIGH Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 20 \mu\text{A}$	2.0V	2.0	1.9	1.9	V	
			4.5V	4.5	4.4	4.4		
			6.0V	6.0	5.9	5.9		
	Q_H	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 4.0 \text{ mA}$ $ I_{OUT} \leq 5.2 \text{ mA}$	4.5V	4.7	3.98	3.84	V	
			6.0V	5.2	5.48	5.34		
	Q_A thru Q_H	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 6.0 \text{ mA}$ $ I_{OUT} \leq 7.8 \text{ mA}$	4.5V	4.2	3.98	3.84	V	
6.0V			5.7	5.48	5.34			
V_{OL}	Maximum LOW Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 20 \mu\text{A}$	2.0V	0	0.1	0.1	V	
			4.5V	0	0.1	0.1		
			6.0V	0	0.1	0.1		
	Q_H	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 4.0 \text{ mA}$ $ I_{OUT} \leq 5.2 \text{ mA}$	4.5V	0.2	0.26	0.33	V	
			6.0V	0.2	0.26	0.33		
	Q_A thru Q_H	$V_{IN} = V_{IH}$ or V_{IL} $ I_{OUT} \leq 6.0 \text{ mA}$ $ I_{OUT} \leq 7.8 \text{ mA}$	4.5V	0.2	0.26	0.33	V	
6.0V			0.2	0.26	0.33			
I_{IN}	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		± 0.1	± 1.0	μA	
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu\text{A}$	6.0V		8.0	80	μA	

Note 4: For a power supply of $5V \pm 10\%$ the worst case output voltages (V_{OH} , and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at $V_{CC} = 5.5V$ and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

$V_{CC} = 2.0V$ to $6.0V$, $C_L = 50$ pF, $t_r = t_f = 6$ ns (unless otherwise specified)

Symbol	Parameter	Conditions	V_{CC}	$T_A = 25^\circ\text{C}$		-40°C to $+85^\circ\text{C}$		Units
				Typ	Guaranteed Limits			
f_{MAX}	Maximum Operating Frequency	$C_L = 50$ pF	2.0V		6	4.8	MHz	
			4.5V		30	24		
			6.0V		35	28		
t_{PHL} , t_{PLH}	Maximum Propagation Delay from SCK to Q'_H	$C_L = 50$ pF	2.0V		150	185	ns	
			4.5V		30	37		
			6.0V		25	31		
t_{PHL} , t_{PLH}	Maximum Propagation Delay from RCK to Q_A thru Q_H	$C_L = 50$ pF	2.0V		150	185	ns	
			2.0V		200	250		
		$C_L = 150$ pF	4.5V		30	37	ns	
			4.5V		40	50		
		$C_L = 50$ pF	6.0V		25	31	ns	
$C_L = 150$ pF	6.0V		34	43				
t_{PHL} , t_{PLH}	Maximum Propagation Delay from $\overline{\text{SCLR}}$ to Q'_H		2.0V		150	185	ns	
			4.5V		30	37		
			6.0V		25	31		
t_{PHL}	Maximum Propagation Delay from $\overline{\text{RCLR}}$ to Q_A thru Q_H	$C_L = 50$ pF	2.0V		125	155	ns	
			4.5V		25	31		
		$C_L = 150$ pF	2.0V		200	250	ns	
			4.5V		40	50		
6.0V		34	43					
t_S	$\overline{\text{SCLR}}$ LOW to RCK		2.0V		50	63	ns	
			4.5V		10	13		
			6.0V		9	11		
t_S	$\overline{\text{RCLR}}$ HIGH to SCK		2.0V		5	5	ns	
			4.5V		5	5		
			6.0V		5	5		
t_S	Minimum Setup Time from SER to SCK		2.0V		90	110	ns	
			4.5V		18	22		
			6.0V		15	19		
t_R	Minimum Removal Time from $\overline{\text{SCLR}}$ to SCK		2.0V		20	20	ns	
			4.5V		10	10		
			6.0V		10	10		
t_S	Minimum Setup Time from SCK to RCK		2.0V		90	110	ns	
			4.5V		18	22		
			6.0V		15	19		
t_H	Minimum Hold Time SER to SCK		2.0V		5	5	ns	
			4.5V		5	5		
			6.0V		5	5		
t_W	Minimum Pulse Width of SCK or $\overline{\text{SCLR}}$ or RCK or $\overline{\text{RCLR}}$		2.0V		100	125	ns	
			4.5V		20	25		
			6.0V		17	21		
t_r , t_f	Maximum Input Rise and Fall Time, Clock		2.0V		1000	1000	ns	
			4.5V		500	500		
			6.0V		400	400		
t_{THL} , t_{TLH}	Maximum Output Rise and Fall Time $Q_A - Q_H$		2.0V		60	75	ns	
			4.5V		12	15		
			6.0V		10	13		
t_{THL} , t_{TLH}	Maximum Output Rise and Fall Time Q'_H		2.0V		75	95	ns	
			4.5V		15	19		
			6.0V		13	16		

AC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC}	T _A = 25°C		-40°C to +85°C	Units
				Typ	Guaranteed Limits		
C _{PD}	Power Dissipation Capacitance, Outputs Enabled (Note 5)	$\bar{G} = V_{CC}$ $\bar{G} = GND$		90			pF
				150			
C _{IN}	Maximum Input Capacitance			5	10	10	pF
C _{OUT}	Maximum Output Capacitance			15	20	20	pF

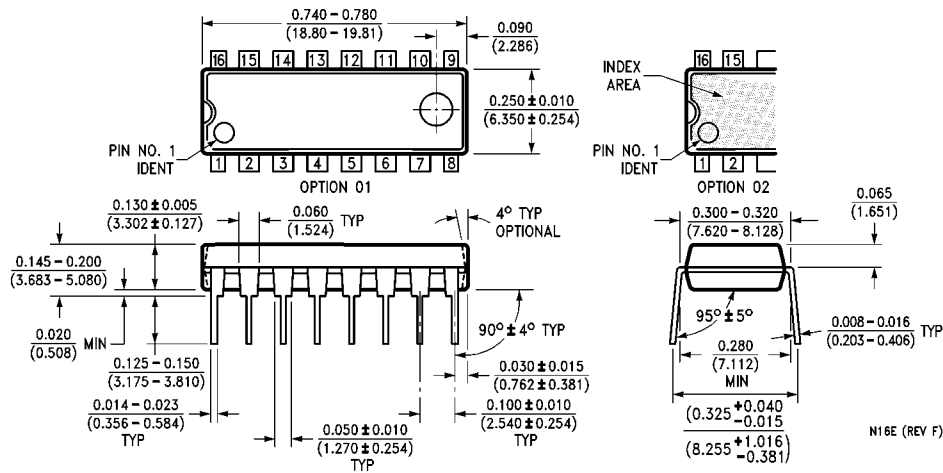
Note 5: C_{PD} determines the no load dynamic power consumption, and the no load dynamic current consumption.

Physical Dimensions inches (millimeters) unless otherwise noted



**16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
Package Number M16A**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N16E

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